



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

K. Kata et al.

Serial No.: 08/533,207

Group Art Unit: 2503

Filed: September 25, 1995

Examiner: M. Prenty

For: PROCESS FOR MANUFACTURING SEMICONDUCTOR DEVICE
AND SEMICONDUCTOR WAFER

Assistant Commissioner of Patents
Washington, D.C. 20231

10/B

7-16-97

T.F

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action mailed February 18, 1997, please amend
the above-identified application as follows:

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JUL 16 1997

IN THE SPECIFICATION:

GROUP 2500

On page 8, line 28, after "chips" insert -- chip electrodes formed on the
opposite side of the semiconductor chips and interconnection layers connecting
the chip electrodes and the bump electrodes, wherein the chip electrodes are not
located directly across the chip from the bump electrodes --.

IN THE CLAIMS:

Please cancel claims 1-4 without prejudice or disclaimer.

5. (Twice Amended) A semiconductor wafer having a plurality of
semiconductor chips, comprising[.] bump electrodes simultaneously formed into
a matrix on an entire surface of the wafer except for on scribe lines between the
semiconductor chips, each semiconductor chip of said semiconductor chips
including:

Sub. Fig. 4
C1 1/2

3
4

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